

## CLAIMS

### What is claimed is:

1. A system in package structure, comprising:
  - a first substrate;
  - a first chip, which is formed on and electrically connected to the first substrate;
  - a first heat-dissipation component having a heat-conducting portion, which is formed above the first chip;
  - a second substrate, which is set above the first heat-dissipating component and electrically connected to the first substrate; and
  - a second chip, which is formed on and electrically connected to the second substrate.
2. The system in package structure of claim 1, further comprising a second heat-dissipating component formed above the second chip.
3. The system in package structure of claim 1, wherein the first substrate has a plurality of first thermal traces and the first heat-dissipation component is connected to the first thermal traces.
4. The system in package structure of claim 1, wherein the second substrate has a plurality of second thermal traces, and the heat-conducting portion protrudes upwardly to contact the second thermal traces.
5. The system in package structure of claim 1, wherein the first heat-dissipating component and the heat-conducting portion are an integrally formed metallic thin plate.
6. The system in package structure of claim 1, wherein the first substrate is a cavity

substrate having a cavity and the first chip is disposed in the cavity.

7. The system in package structure of claim 1, wherein at least one bump is formed between the first substrate and the second substrate and electrically connects the first substrate and the second substrate.
8. The system in package structure of claim 1, further comprising an electrical connection board provided between the first substrate and the second substrate, and electrically connected the first substrate and the second substrate.
9. The system in package structure of claim 8, further comprising a first bump for electrically connecting the electrical connection board and the first substrate.
10. The system in package structure of claim 8, further comprising a second bump for electrically connecting the electrical connection board and the second substrate.